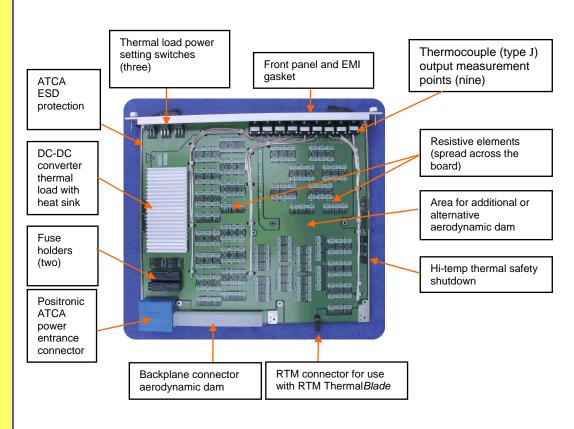


ADVANCEDTCA THERMAL BLADE

Product Overview

The F9 Systems, Inc. Thermal Blade offers the flexibility to verify the airflow, power load and thermal characteristics of your AdvancedTCA (ATCA) chassis, logic cards and backplane designs. It emulates typical application component heights and features to enable airflow and thermal analysis. A variety of independently controlled power conditions are provided for in-depth power management. The Thermal Blade is a critical tool for ATCA compliance engineering during system design and manufacturing test.



Thermal Blade Key Product Features

- AdvancedTCA compatible design.
- Test airflow, power load and thermal performance of your chassis, logic cards and backplane.
- Provides a thermal load of up to 200 watts per slot from a redundant ATCA –48 VDC backplane.
- Operates over the entire –36 to –72 VDC voltage range without damage to the thermal board.
- Mimics aerodynamics of a typical high performance board.

- User switchable variable thermal load choices of zero, 1/3, 2/3 and full load are provided to test the power and thermal capabilities of an ATCA system and chassis.
- Provision for up to 50 watts connection to the RTM Thermal Blade (available separately).
- Nine on-card thermal measurement points.
- All UL and IEC safety design features are incorporated, including fusing, thermal shutdown, and adequate copper weight.